imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





157 Series – Standard Nano^{2®} Fuse and Clip Assembly



Agency Approvals				
AGENCY	AGENCY FILE NUMBER	AMPERE RANGE		
c SL [®] us	E14721	0.062A ~ 10A		
PSE	NBK030205-E10480A NBK030205-E10480B NBK101105-E184655	1A - 1.6A 2A - 5A 6.3A - 10A		

Electrical Characteristics for Series

Electrical Specifications by Item

% of Ampere Rating	OpeningTime at 25°C
100%	4 hours Minimum
200%	5 secs. Maximum

Description

The 157 Series - Standard Nano Fuse/Clip assembly is a small, square, very fast acting surface mount fuse that is assembled in surface mountable fuse clips. The fuse clip and pre-installed fuse combination can be automatically placed in PC Board in one efficient manufacturing operation. It permits quick and easy replacement of fuses without performing desoldering process, even in the field and without exposing the PC Board to detrimental effects of rework solder heat.

Features

- Surface Mountable, Very Fast Acting Fuse.
- Fully compatible with RoHS/Pb-Free solder alloys and higher temperature profiles associated with leadfree assembly.
- Easily replaceable on PC Board (Field Replaceable)

ROHS HF CALUS CPS

- RoHS compliant and Halogen Free
- Available in ratings of 0.062 ~ 10 Amperes.

Applications

- Instrumentation
- B
- Telecommunications

Base	Stations	
Base	Stations	

Ampere	Amp Max Voltage Interrupting	Fuse	Nominal Cold	Nominal	Agency A	pprovals		
Rating (A)	Code	Rating (V)	Rating (A)		Resistance (Ohms)	Melting I²t (A²sec)	c 🔊 us	PSE
0.062	.062	125		0451.062	5.5372	0.00019	Х	
0.080	.080	125		0451.080	4.0500	0.00033	X	
0.100	.100	125		0451.100	3.1000	0.00138	X	
0.125	.125	125		0451.125	1.7059	0.00286	X	
0.160	.160	125		0453.160	1.2157	0.0048	Х	
0.200	.200	125		0453.200	1.3971	0.00652	X	
0.250	.250	125		0453.250	1.0496	0.01126	X	
0.315	.315	125		0453.315	0.3881	0.0311	X	
0.375	.375	125		0453.375	0.6100	0.0442	X	
0.400	.400	125		0453.400	0.5600	0.0551	X	
0.500	.500	125		0453.500	0.4200	0.0824	X	
0.630	.630	125		0453.630	0.3050	0.1381	X	
0.750	.750	125	50A @ 125 VAC/VDC	0453.750	0.2450	0.2143	X	
0.800	.800	125	JUA @ 123 VAC/VDC	0453.800	0.2120	0.2654	X	
1.0	001.	125	300A @ 32 VDC	0453001.	0.1530	0.6029	X	Х
1.25	1.25	125	300A @ 32 VDC	04531.25	0.078	0.664	X	Х
1.5	01.5	125		045301.5	0.0634	0.853	X	Х
1.6	01.6	125		045301.6	0.0580	1.060	X	Х
2.0	002.	125		0453002.	0.0373	0.530	X	Х
2.5	02.5	125		045302.5	0.0288	1.029	X	Х
3.0	003.	125		0453003.	0.0229	1.650	X	Х
3.15	3.15	125		04533.15	0.0215	1.920	X	Х
3.5	03.5	125		045303.5	0.0203	2.469	X	Х
4.0	004.	125		0453004.	0.0163	3.152	X	Х
5.0	005.	125		0453005.	0.0127	5.566	X	Х
6.3	06.3	125		045306.3	0.0098	9.17	X	Х
7.0	007.	125		0453007.	0.0092	10.32	X	Х
8.0	008.	125		0453008.	0.0079	20.23	X	X
10.0	010.	125	35A @ 125 VAC / 50A @125 VDC 300A @ 32VDC	0453010.	0.0058	26.46	X	Х

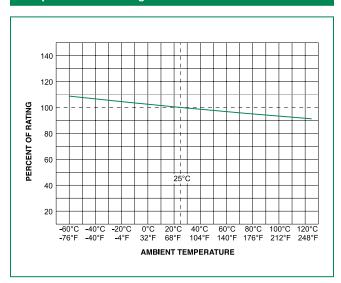
1. Cold resistance measured at less than 10% of rated current at 23°C. I2t values stated for 8ms opening time

3. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved ial electrical characteristic needs? Contact Littelfuse to learn more about application specific options.

Surface Mount Fuses NANO^{2®} > 157 Fuse and Holder Combination

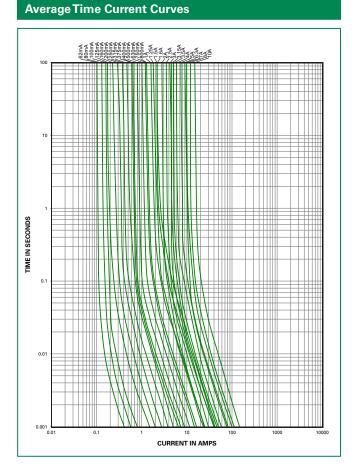


Temperature Re-rating Curve



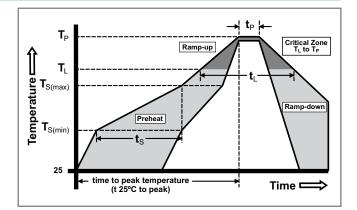
Note:

1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.



Soldering Parameters

Reflow Co	ndition	Pb – Free assembly
	-Temperature Min (T _{s(min)})	150°C
Pre Heat	-Temperature Max (T _{s(max)})	200°C
	-Time (Min to Max) (t _s)	60 – 120 secs
Average ra (T _L) to pea	amp up rate (LiquidusTemp k	5°C/second max.
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.
Reflow	-Temperature (T _L) (Liquidus)	217°C
Reliow	-Temperature (t _L)	60 – 90 seconds
PeakTemperature (T _P)		260+0/-5 °C
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T _P)		8 minutes max.
Do not exceed		260°C





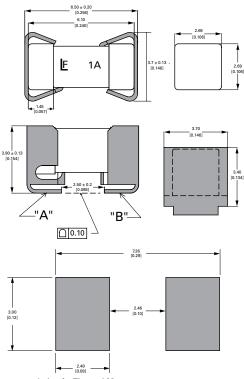
Surface Mount Fuses NANO^{2®} > 157 Fuse and Holder Combination

Product Characterist	ics
-----------------------------	-----

Body: Ceramic Cap: For 0.062A ~ 0.125A – Au plated Bra For 0.200A ~ 10A – Silver plated Bra Clip Plating: Matte Tin		
Product Marking	Body: Brand Logo, Current Rating	
Clip Retention	Force applied at fuse center, perpendicular to the long axis (@ 0.75 lbs. MIN)	
Solderability	MIL-STD-202, Method 208 / IPC/ EIA / JEDEC J-STD-002, Test Condition A	
Humidity Test	MIL –STD-202, Method 103 @ 85°C / 85%RH, 1000 hours	
Resistance to Solvents	MIL-STD-202, Method 215 (3 solvent types)	

Operating Temperature	-55°C to 125°C with proper derating
Thermal Shock	MIL-STD-202, Method 107, Test Condition B (5 cycles -65°C to +125°C)
Vibration	MIL-STD-202, Method 201 (10-55 Hz)
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles
Salt Spray/ Atmosphere	MIL-STD-202, Method 101, Test Condition B (48 hrs.), 5% NaCl in De-ionized Water
Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)

Dimensions



PCB Recommendation for Thermal Management

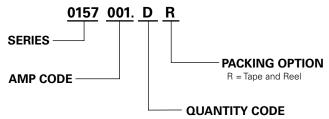
1. Minimum Copper Layer Thickness = 100um

2. Minimum Copper Trace Width = 10mm

Note:

Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed 80°C in a 25°C ambient environment.

Part Numbering System



D = 1500 pcs

Packaging			
Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
Tape and Reel	Surface Mount	1500	DR

Resources

Additional Information





Samples